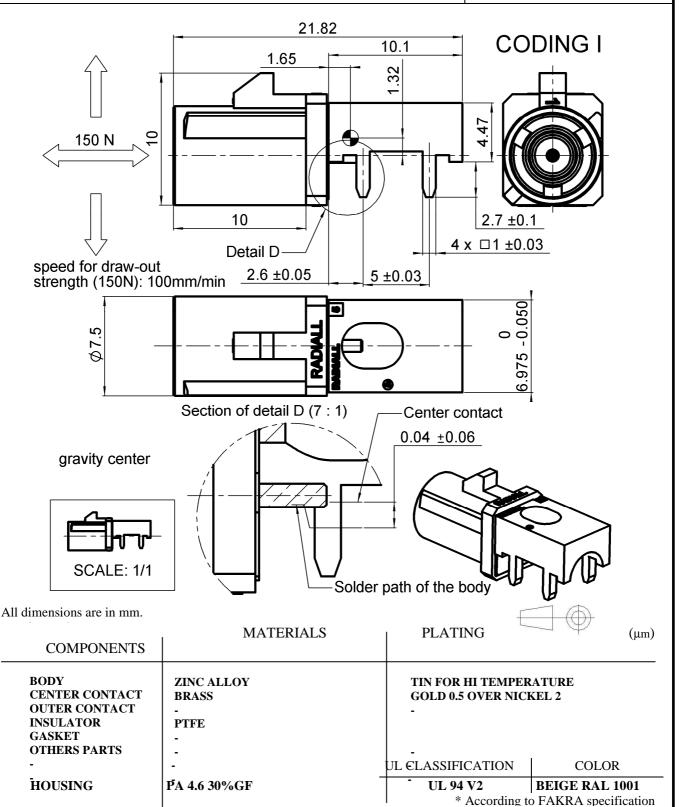
EDGE CARD - PIN IN PASTE VERSION

R197.160.I18

Series : SMB CARLOCK



Issue: 0943 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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R197.160.I18

Series : **SMB CARLOCK**

PACKAGING

Standard	Unit	Other
350	'W' option	Contact us

SPECIFICATION

QS9000 SN 55228-2**

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency **0-4** GHz VSWR **1.06*** + **0.0130** x F(GHz

VSWR 1.06* + 0,0130 x F(GHz) Maxi Insertion loss 0.03* $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (- F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+110 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

*COAX TRANSMISSION LINE ONLY
**Complaint except that 2D label does
not include the shipping note number.

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 50 Cycles mini

Weight 2,2297 g

CUSTOMER'S APPROVAL

Department or company's stamp

Name:
Date:

Copy to send back to RADIALL S.A. BEFORE:

23/02/2006

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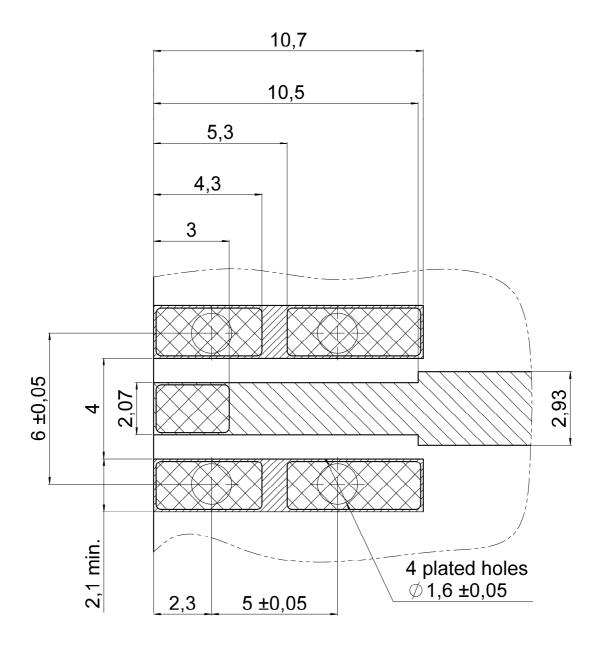


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MOUNTING ZONE FOR RECEPTACLE



Thickness of PCB: 1,6 mm. Material of PCB: FR4 ($\epsilon r = 4.6$). Solder paste has to be printed onto the land of solder and into holes to permit Pin In Hole Reflow

/////// Grou

Ground track



Signal track



Land for solder

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1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

SOLDER PROCEDURE

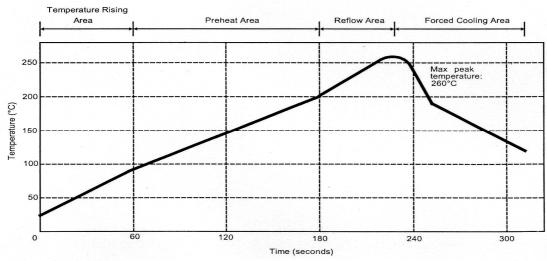
We advise a thickness of 0.2 millimetres min. (0.008 inch min.). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec

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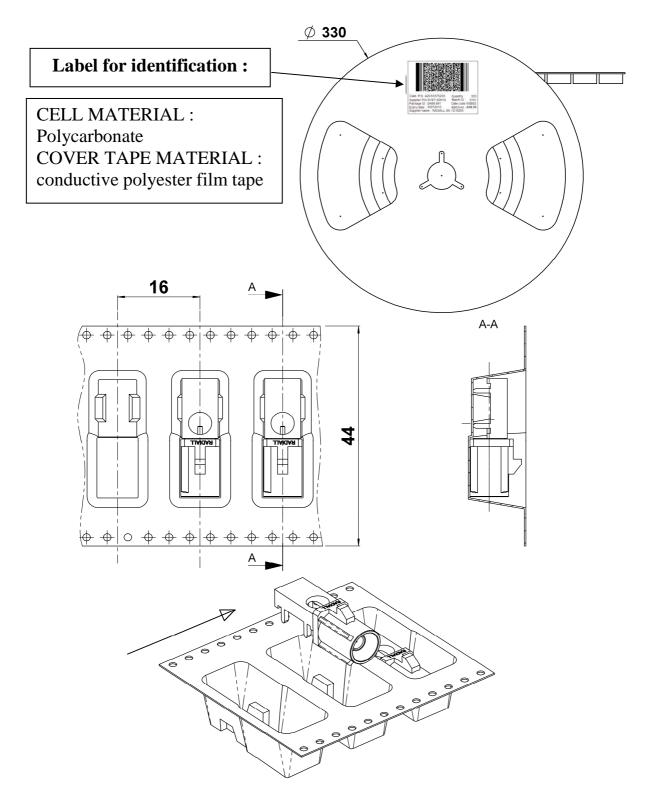


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REEL PACKAGING PER 350



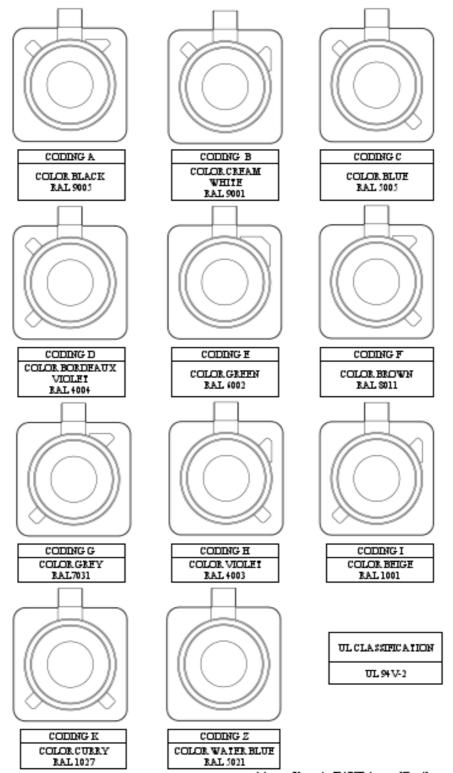
Issue: 0943 C In the effort to improve our products, we reserve the right to make changes judged to be



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*According to FAKRA specifications

To obtain other coding for the connector please change the letter by the needed coding letter into the Part Number

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